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Tacky
Pressure Sensitive
Electrically Conductive
Non Curing
Film Adhesive

IDEAL FOR:

- Component Attach
- Heat Sink Attach
- Substrate Attach

DESCRIPTION:

TP8205 is a silver filled, low bond strength thermoplastic film adhesive. It is designed for bonding heat sink, component, and substrate. It is electrically and thermally conductive.

AVAILABILITY:

TP8205 is available in sheet sizes or as custom preforms. Standard thicknesses are 0.004" and 0.006". Special thicknesses are available. TP8205 can be obtained in liquid form (LTP8205). This product is fiberglass reinforced.

APPLICATION PROCEDURES:

- (1) Cut or pre-cut to desired size.
- (2) Remove one side of release paper from adhesive.
- (3) Place on substrate or component with rolling finger pressure, then remove the other release paper.
- (4) Place component on substrate with insertion pressure of 15 psi or more.

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details. The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

THERMOPLASTIC FILM
TP8205

TYPICAL PROPERTIES*

Electrical Resistivity (25 °C/1 minute)	<5x10 ⁻² ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	-25 ±10%
Lap-Shear Strength	>100 psi >0.69 N/mm ²
Device Push-off Strength	200 psi ±10% 1.4 N/mm ² ±10%
Cured Density (gm/cc)	3.0 ±10%
Hardness (Type)	<40 (A) ±10%
Thermal Conductivity	40 Btu-in/hr-ft ² -°F ±10% 5.7 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	110 ±15%
Tensile Modulus:	
Maximum Continuous Operation Temp. (°C)	<150

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CURE SCHEDULES:

Temperature	Time	Pressure
None		

SHELF LIFE:

Storage temperature	Shelf Life
25°C	1 yr